



Embedded SSD Product Challenges and Test Mitigation

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Overview



- Embedded SSD Product Challenges
 - The Factor of Industry Focus & Validation Challenges
 - The Factor of Memory Transition
- Embedded SSD Mitigation
 - Full Scale Testing Product Development
 - Full Scale Testing Mass Production



The Factor of Industry Focus & Validation Challenges



- NAND Industry Focus
 - Trend Controller / NAND Design:
 - Higher ECC requirements and other NAND controller requirements such as data randomization and Read Retry/Recovery Functions
 - Focus on maximizing endurance/cycling
 - Trend / SSD Level:
 - The cost advantages of die shrink with progressively higher densities to maintain ASP
 - Focus on enterprise and client usage models



The Factor of Industry Focus & Validation Challenges



- Less attention to
 - Escalation of validation costs on newer process node
 - Change of reliability characteristics -> wider test coverage due to added variables, larger sample siz, longer testing periods, attention to lower industry attention areas, especially *data retention*
 - Maintained production level screening system for DPM stability





The Factor of Memory Transition

• Reduce Endurance and Increase ECC requirement





The Factor of Memory Transition

Indispensable Read Retry Function









(Average 2.5" SSD Density)











Embedded SSD Tendencies

Typically Smaller Density Requirements

Often Smaller file sizes data transfers

Workload Tendencies Toward Random Write





Typically Smaller Density Requirements

Often Smaller file sizes data transfers

Workload Tendencies Toward Random Write Risk of Performance Erosion

Risk of Higher WAI

and Endurance Issues



Risk of Power Failure





- Lost File Allocation Table
- Disk cannot be found





- Mitigation on Product
 - Overprovisioning
 - Maintained user space with larger on board NAND usage
 - Multi-plane NAND
 - 2 plane and now 4 plane organized NAND
 - Utilization of controller cache
 - Firmware optimized per usage model
 - Firmware optimization by usage model
 - Auto-scan, auto-refresh, early refresh algorithms in addition to traditional wear leveling





Embedded SSD Mitigation: Test Area Deep Dives

IC/SSD Validation



 Ensuring the reliability & function of new NAND die + SSD

Mass Production



 Screening out defects & assuring complete reliability at scale



Mitigation: Full Scale Testing (SSD Validation)

- IC Level Test, Confirmed at SSD Level
 - Reliability characteristics (Endurance, Read Disturb, Data Retention) over wide temperatures, and Cross temperature
 - Set up spec, criteria and features for SSDs





Mitigation: Full Scale Testing (SSD Validation)

- SSD Level Test (1)
 - Performance: Lower/middle densities and a lower CE count for embedded/industrial application SSDs.
 - Endurance: NAND trending continues towards larger page size (8K/16K) and embedded/Industrial usage models are often utilizing much smaller file transfers. This can result in a very different write amplification factor which affects the endurance of the SSD.



Mitigation: Full Scale Testing (SSD Validation)

- SSD Level Test (2)
 - Power Fail Factors
 - Stand-alone HW solution, Industrial grade capacitors w/o degradation or flammability concern
 - Power Cycling RDT
 - Sudden, targeted power-off in <u>write/erase</u> operations
 - <u>Multiple test patterns & Random</u> power off delay timing
 - Power On/Off Test
 - Simulate sudden power off in <u>read</u> operations (OS boot-up application)





Mitigation: Full Scale Testing (Mass Production)

- Reliable and scalable MP validation
 - Proper production level screening mechanisms to ensure quality
- Challenges
 - Trade off between SSD production burn in time versus operational efficiency
 - Variance of NAND RBER (Raw Bit Error Rate) and ELFR (Early Life Failure Rate) as process matures
 - Variance in the same factors by wafer production lot / date code





Mitigation: Full Scale Testing (Mass Production)

- Mitigation: Efficiency in Test
 - Capability to utilize intelligent production level test based on NAND characteristics rather than pure brute force copy/compare



exceeding pre-set ECC threshold





Mitigation: Full Scale Testing (Mass Production)

- Mitigation: Efficiency in Test
 - Capability to utilize acceleration factor of temperature during burn in
 - Experience building to further optimize test over volume and process mature



Higher Temperature: Burn in Acceleration Factor Temperature Cycling: Production/Assembly Quality



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